



Attorney's Docket No. 038190/241788

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re:	Slemmons et al.	Confirmation No.:	9245
Appl. No.:	10/005,633	Group Art Unit:	2827
Filed:	December 5, 2001	Examiner:	D. Graybill
For:	MICROBEAM ASSEMBLY FOR INTEGRATED CIRCUIT INTERCONNECTION TO SUBSTRATES		

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March 18, 2003

Commissioner for Patents
Washington, DC 20231

AMENDMENT

Sir:

Please amend the above-identified patent application as follows:

In The Claims:

Please cancel Claim 30 and please amend Claims 25 and 26 as follows:

25. A microbeam assembly adapted to form interconnects between integrated circuit bond pads and substrate contacts, the microbeam assembly comprising:

a carrier;

a release layer located on said carrier, said release layer being etchable; and

a plurality of conductive microbeams releasably bonded to said release layer, wherein the conductive microbeams are sized and spaced to mate with the bond pads of an integrated circuit, and wherein said microbeams are releasable from said carrier by at least partially etching away said release layer.

26. A microbeam assembly according to Claim 25 wherein the carrier is a tape automated bonding (TAB) carrier and said release layer is formed from a material selected from the group consisting of polyimide and parylene.

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